

METHOD OF MANUFACTURING DEVICE-EMBEDDED BOARD AND DEVICE-EMBEDDED BOARD

ABSTRACT

A method of manufacturing a device-embedded board includes: steps S10 to S30 of preparing an electronic device 10, an inner board 40 and outer boards 50B and 60B; a step S40 of temporarily fixing the electronic device 10 to the outer board 50B; a step S50 of stacking the outer boards 50B and 60B and the inner board 40 with each other so that the electronic device 10 is inserted into the first opening 411; and a step S60 of fixing the outer boards 50B and 60B and the inner board 40 to each other. The electronic device 10 includes: a device main body 20; an insulating layer 33 having an opening 331; and a wiring layer 34 disposed on the insulating layer 33 to cover the opening 331. The second step S40 includes pressing the electronic device 10 against the outer board 50B in a state in which the conductive paste 55B is in contact with the wiring layer 34.

Fig. 4